

LMP3385XF 30V P-Channel MOSFET

Features

- -30V/-54A, $R_{DS(ON)}$ <8m\O@V_{GS}=-10V
- Fast switching
- Suit for -4.5V Gate Drive Applications
- Green Device Available
- DFN5X6-8L package design

Product Description

These P-Channel enhancement mode power field effect transistors are using trench DMOS technology. This advanced technology has been especially tailored to minimize on-state resistance,

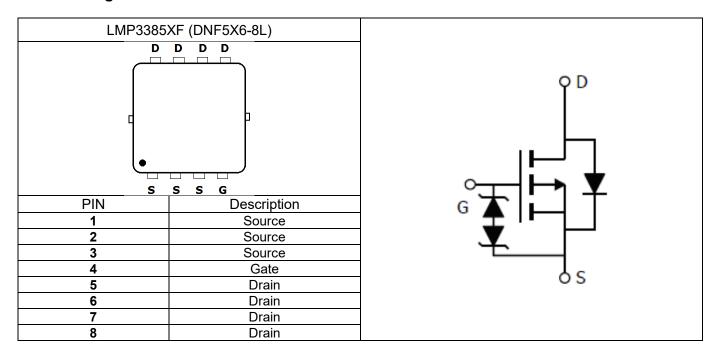
provide superior switching performance, and withstand high energy pulse in the avalanche and commutation mode.

These devices are well suited for high efficiency fast switching applications.

Applications

- Motor Driver Applications
- POL Applications
- Load Switch
- LED Application

Pin Configuration





Ordering Information

Ordering Information					
Part Number	P/N	PKG code	Pb Free code	Package	Quantity
LMP3385XF	LMP3385	Х	F	DFN5X6-8L	3000

Marking Information

Marking Information				
Part Marking	Part Number	LFC code		
3385XF	3385XF	XWMMMM		
XWMMMM	0000/4	XVVIVIIVIIVIIVII		

Absolute Maximum Ratings

(T_C=25°C Unless otherwise noted)

Symbol	Parameter		Typical	Unit
V _{DS}	Drain-Source Voltage		-30	V
V_{GS}	Gate-Source Voltage		±25	V
I _D	Continuous Drain Current	T _C =25°C	-54	A
		Tc=100°C	-34	
I _{DM}	Pulsed Drain Current ¹		-180	А
P _D F	Power Dissipation	T _C =25°C	37.9	W
		T _C =100°C	15.2	***
TJ	Operating Junction Temperature Range		-55 to +150	$^{\circ}$
T _{STG}	Storage Temperature Range		-55 to +150	${\mathbb C}$
R _{eJC}	Thermal Resistance-Junction to Case		3.3	°C/W

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Electrical Characteristics

(T_C=25°C Unless otherwise noted)

Symbol	Parameter	Conditions	Min	Тур	Max	Unit		
	Static characteristics							
$V_{(BR)DSS}$	Drain-Source Breakdown Voltage	V _{GS} =0V, I _D =-250uA	-30			V		
$V_{\text{GS(th)}}$	Gate Threshold Voltage	$V_{DS}=V_{GS}$, $I_{D}=-250uA$	-1.2	-1.6	-2.5	V		
Igss	Gate Leakage Current	V _{DS} =0V, V _{GS} =±25V			±100	nA		
I _{DSS}	Drain-Source Leakage Current	V _{DS} =-30V, V _{GS} =0V			-1	uA		
V _{SD}	Diode Forward Voltage ³	V _{GS} =0V, I _S =-1A			-1	V		
D-ac	Drain-Source On-Resistance ³	V _{GS} =-10V, I _D =-10A		6.9	7.8	mΩ		
R _{DS(on)}		V _{GS} =-4.5V, I _D =-6A		10.7	12.3			
Gate charge characteristics								
Qg	Total Gate Charge ^{3,4}	15)/ 16)/		68		nC		
Q _{gs}	Gate-Source Charge ^{3,4}	V _{DD} =-15V, V _{GS} =10V, I _D =-15A		10				
Q _{gd}	Gate-Drain Charge ^{3,4}			12				
Dynamic characteristics								
Ciss	Input Capacitance	V _{DS} =-15V,V _{GS} =0V,		4319		pF		
Coss	Output Capacitance	f=1.0MHz		439				
C_{rss}	Reverse Transfer Capacitance			299				
t _{d(on)}	Turn-On Time			12		- ns		
t _r	Rise Time	V _{DD} =-15V, V _{GS} =-10V,		11				
$t_{d(off)}$	Turn-Off Time	Rg=3.3 Ω , I _D =-15A		105		_		
t _f	Fall Time			21				



Typical Performance Characteristics

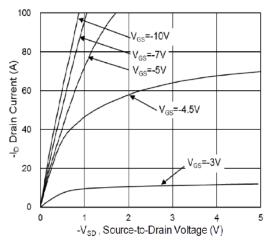


Figure 1. Output Characteristics

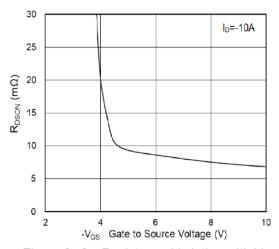


Figure 2. On-Resistance Variation with V_{GS}

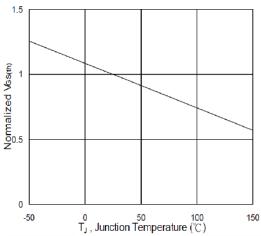


Figure 3. Normalized V_{GS(th)} vs. T_J

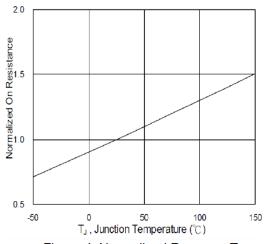


Figure 4. Normalized RDSON vs. TJ

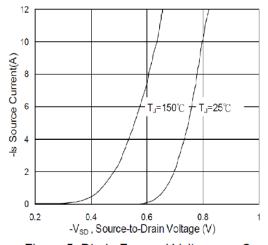


Figure 5. Diode Forward Voltage vs. Current

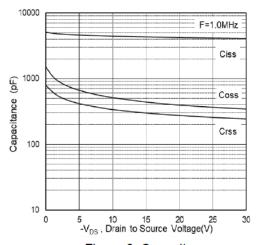


Figure 6. Capacitance



Typical Performance Characteristics(continue)

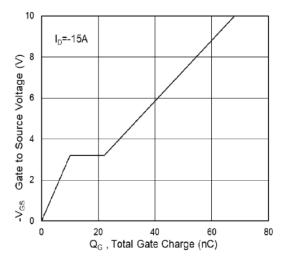


Figure 7. Gate Charge Waveform

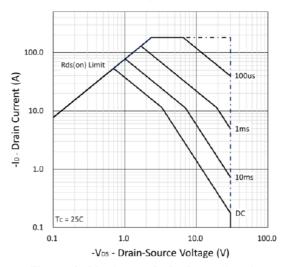


Figure 8. Maximum Safe Operating Area

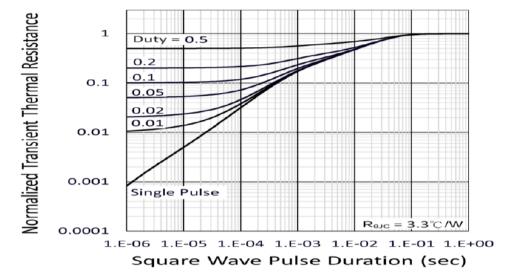
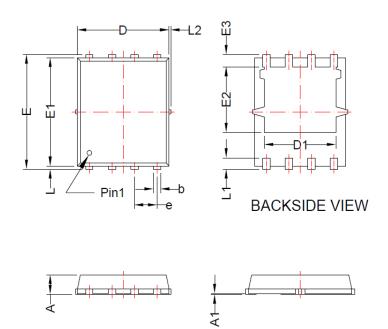


Figure 9. Normalized Transient Thermal Resistance



Package Dimension:

DFN5X6-8L



DIMENSION D AND E1 DOES NOT INCLUDE MOLD FLASH, PROTRUSIONS OR GATE BURRS. MOLD FLASH, PROTRUSIONS OR GATE BURRS SHALL HOT EXCEED $0.5 \mathrm{mm}$ PER INTERLEAD FLASH OR PROTRUSIOB SHALL NOT EXCEED $0.5 \mathrm{mm}$ PER SIDE.

		Dimensions		
SYMBOL	Millimeters		Incl	nes
	MIN	MAX	MIN	MAX
Α	0.80	1.20	0.031	0.047
A1	0.00	0.05	0.000	0.002
b	0.25	0.51	0.010	0.020
С	0.20	0.35	0.008	0.014
D	4.90	5.40	0.193	0.213
D1	3.40	4.60	0.134	0.181
E	5.90	6.20	0.232	0.244
E1	5.40	5.90	0.213	0.232
E2	3.20	3.80	0.126	0.150
E3	0.40	0.80	0.016	0.031
H1	1.27 BSC		0.050 BSC	
L	0.1	0.25	0.004	0.010
L1	0.45	0.75	0.018	0.030
L2		0.15		0.006

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